

Notices

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This section of the FEDERAL REGISTER contains documents other than rules or proposed rules that are applicable to the public. Notices of hearings and investigations, committee meetings, agency decisions and rulings, delegations of authority, filing of petitions and applications and agency statements of organization and functions are examples of documents appearing in this section.

COMMISSION ON CIVIL RIGHTS

Notice of Public Meeting of the South Carolina Advisory Committee to the U.S. Commission on Civil Rights

AGENCY: U.S. Commission on Civil Rights.

ACTION: Notice of virtual business meeting.

SUMMARY: Notice is hereby given, pursuant to the provisions of the rules and regulations of the U.S. Commission on Civil Rights (Commission) and the Federal Advisory Committee Act, that the South Carolina Advisory Committee (Committee) to the U.S. Commission on Civil Rights will hold a public meeting via Zoom. The purpose is to discuss the implementation stage and debrief on the testimony as part of their study on Occupational Licensing.

DATES: Monday, September 28, 2026, from 3:00 p.m.–4:30 p.m. Eastern Time.

ADDRESSES: The meeting will be held via Zoom.

Registration Link (Audio/Visual):
https://www.zoomgov.com/webinar/register/WN_maCuOYKOQFiHGzRn8Tifyg.

Join by Phone (Audio Only): 1–833–435–1820 USA Toll Free; Webinar ID: 165 439 4019#.

FOR FURTHER INFORMATION CONTACT: Victoria Moreno, Designated Federal Officer, at vmoreno@usccr.gov or (434) 515–0204.

SUPPLEMENTARY INFORMATION: This Committee meeting is available to the public through the registration link above. Any interested members of the public may attend this meeting. An open comment period will be provided to allow members of the public to make oral comments as time allows. Pursuant to the Federal Advisory Committee Act, public minutes of the meeting will include a list of persons who are present at the meeting. If joining via phone, callers can expect to incur regular

charges for calls they initiate over wireless lines, according to their wireless plan. The Commission will not refund any incurred charges. Callers will incur no charge for calls they initiate over land-line connections to the toll-free telephone number. Closed captioning is available by selecting “CC” in the meeting platform. To request additional accommodations, please email csanders@usccr.gov at least 10 business days prior to the meeting.

Members of the public are entitled to submit written comments; the comments must be received in the regional office within 30 days following the scheduled meeting. Written comments may be submitted via the following form: <https://wkf.ms/4n7DKT3>. Persons who desire additional information may contact the Regional Programs Coordination Unit at (434) 515–0204.

Records generated from this meeting may be inspected and reproduced at the Regional Programs Coordination Unit Office, as they become available, both before and after the meeting. Records of the meetings will be available via the file sharing website, <https://usccr.box.com/s/uc7rr59hi2y8p1uapge mt6y1opr61zyv>. Persons interested in the work of this Committee are directed to the Commission’s website, <http://www.usccr.gov>, or may contact the Regional Programs Coordination Unit at csanders@usccr.gov.

Agenda: Will be available at the following link in advance of the meeting date—<https://usccr.box.com/s/v6q5obt9z q1jr0hs3pj5h9757y9s0zmf>.

Dated: August 19, 2026.

David Mussatt,

Supervisory Chief, Regional Programs Unit.

[FR Doc. 2026–17197 Filed 8–21–26; 8:45 am]

BILLING CODE P

DEPARTMENT OF COMMERCE

Foreign-Trade Zones Board

[B–104–2026]

Foreign-Trade Zone (FTZ) 183, Notification of Proposed Production Activity; Ichor Systems, Inc.; (Semiconductor Equipment); Austin, Texas

Ichor Systems, Inc. submitted a notification of proposed production activity to the FTZ Board (the Board) for

its facility in Austin, Texas within FTZ 183. The notification conforming to the requirements of the Board’s regulations (15 CFR 400.22) was received on July 30, 2026.

Pursuant to 15 CFR 400.14(b), FTZ production activity would be limited to the specific foreign-status material(s)/ component(s) and specific finished product(s) described in the submitted notification (summarized below) and subsequently authorized by the Board. The benefits that may stem from conducting production activity under FTZ procedures are explained in the background section of the Board’s website—accessible via www.trade.gov/ftz.

The proposed finished products include: shutoff or control valves for gas panel of semiconductor wafer fabrication equipment; gas panels for semiconductor wafer fabrication equipment/machines; weldments for gas panels of semiconductor wafer fabrication equipment (vaporizer, gas lines); assembly kits of gas panel for semiconductor wafer fabrication equipment/machines; stainless steel tube/pipe fittings; hand-operated valves for gas panels; parts of hand-operated gas valves for gas panels; other parts of gas valves for gas panels; pressure-reducing valves; gas filtering/purifying machinery; automatic regulating instruments/apparatus; optical fiber cables; parts of filtering/purifying machinery for gas panels; electrical switches installed onto gas panels; stainless steel seamless pipe/tube used for the assembly of gas panels; larger stainless steel seamless pipe/tube (>19mm) used for the assembly of gas panels; flexible tubing of iron or steel used for the assembly of gas panels; stainless steel butt welding fittings used for the assembly of gas panels; rubber hoses reinforced with textile materials used for the assembly of gas panels; stainless steel seamless tubes/pipes used for the assembly of gas panels; smaller stainless steel welded pipe/tube (<1.65mm) used for the assembly of gas panels; insulated electric conductors with connectors used for the assembly of gas panels; ignition wiring sets and other wiring sets used for the assembly of gas panels; electrical plugs or sockets or connectors used for the assembly of gas panels; stainless steel flanges used for the assembly of gas panels; steel springs used for the assembly of gas

panels; stainless steel threaded elbows/bends/sleeves used for the assembly of gas panels; steel weldments used for the assembly of gas panels; gas panels for manufacture of semiconductor devices; pneumatic power valves; gas valves for semiconductor equipment; glass for gas panel windows; insulated electric conductors with connectors; gas panels for semiconductor wafer fabrication equipment; automatic regulating instruments/apparatus; stainless steel bars/rods; stainless steel seamless tube/pipe; back planes and gas or chemical panel frames for semiconductor manufacturing equipment; stainless steel butt welding fittings used for the assembly of gas panels; stainless steel seamless tube/pipe used for the assembly of gas panels; mechanical seals used for the assembly of gas panels; gas valves used for the assembly of gas panels; wired glass sheets used for the assembly of gas panels; wooden crates used to package gas panels for shipping; processing units for adp machines; steel weldments for semiconductor equipment; and parts of machinery for working rubber/plastics used for the assembly of gas/chemical panels (duty rate ranges from duty-free to 5.6%).

The proposed foreign-status materials/components include: polymer-based prepared adhesive compound in liquid or paste form used for bonding and sealing semiconductor equipment assemblies and fluid handling hardware; plastic bar (nylon hexago) used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; rigid polyvinyl chloride plastic pipe or tube used for industrial chemical distribution and process utility systems in semiconductor fabrication facilities; extruded plastic tube, pipe, hose, elbow, coupling, or connector fitting used in semiconductor gas, liquid chemical, or vacuum delivery systems; rigid or flexible polyethylene plastic tubing and hose used for low-pressure chemical and gas transfer applications in semiconductor manufacturing equipment; pressure-sensitive plastic sheet, tape, film, or adhesive-backed material used for insulation, sealing, masking, or protective applications in semiconductor manufacturing; polycarbonate plastics used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; polyurethane plastics used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications;

molded plastic container, bag, tray, cap, closure, or packaging article used for handling, protecting, and transporting semiconductor components and assemblies; molded plastic container, bag, tray, cap, closure, or packaging article of polymers of ethylene used for handling, protecting, and transporting semiconductor components and assemblies; fabricated plastic articles including spacers, retainers, insulators, guards, or protective hardware used in semiconductor process equipment; vulcanized rubber gasket, seal, o-ring, or sealing ring designed for vacuum integrity and chemical containment in semiconductor fluid handling systems; industrial labels used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; industrial felt (polyester) or nonwoven textile pad used for filtration, insulation, vibration damping, or protective lining in semiconductor manufacturing equipment; technical ceramic tube, insulator, chamber component, or wear-resistant article used in semiconductor process and vacuum systems; deionized water tank used in semiconductor electrical and thermal management applications; fabricated glass or quartz article including windows, covers, shields, or chamber components used in semiconductor manufacturing equipment; fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (electroslag or vacuum arc remelted); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (containing 8percent or more but less than 24 percent by weight of nickel); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (less than 18mm and containing 8 percent or more but less than 24 percent by weight of nickel); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (18mm or more and containing 8 percent or more but less than 24 percent by weight of nickel); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (containing 8percent or more but less than 24

percent by weight of nickel); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (less than 152.4mm and containing less than 8 percent by weight of nickel); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (of a thickness of less than 4.75 mm > other of a thickness of less than 4.75 mm); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (of a thickness of less than 4.75 mm > of a width of less than 300 mm); fabricated stainless-steel bar, plate, tube, fastener, spring, or structural article used in semiconductor manufacturing equipment assemblies (nickel-alloy); seamless stainless-steel tube or pipe manufactured for high-purity gas, vacuum, and corrosive chemical transfer applications in semiconductor fabrication (of an external diameter of less than 19 mm > other of an external diameter of less than 19 mm); seamless stainless-steel tube or pipe manufactured for high-purity gas, vacuum, and corrosive chemical transfer applications in semiconductor fabrication; seamless stainless-steel tube or pipe manufactured for high-purity gas, vacuum, and corrosive chemical transfer applications in semiconductor fabrication (having a wall thickness of 4 mm or more > of alloy steel); stainless steel tube or pipe fitting including elbows, reducers, couplings, tees, or adapters used in semiconductor gas and chemical distribution systems; machined stainless-steel flange with precision sealing surfaces used for connecting semiconductor gas and chemical process piping systems; threaded stainless steel pipe connection fitting for high-purity semiconductor gas and fluid delivery systems; threaded stainless steel pipe connection fitting for high-purity semiconductor gas and fluid delivery systems (spring washers and other lock washers); threaded stainless steel pipe connection fitting for high-purity semiconductor gas and fluid delivery systems (cotters and cotter pins); copper alloy tube or pipe fitting designed for controlled gas, cooling water, or fluid transfer systems in semiconductor equipment; copper screws, pins, and washers used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; copper screws, pins, and washers used in semiconductor manufacturing, fluid

handling, vacuum processing, or industrial automation applications (having shanks, threads or holes less than 6 mm in diameter); copper screws, pins, washers used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; nickel plates/sheets used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; nickel tubes/pipes used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; nickel pipes and pipe fittings used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; flat-rolled or extruded aluminum alloy plate, sheet, bar, or profile used in semiconductor equipment frames, panels, and structural assemblies; flat-rolled or extruded aluminum alloy plate, sheet, bar, or profile used in semiconductor equipment frames, panels, and structural assemblies (body stock); flat-rolled or extruded aluminum alloy plate, sheet, bar, or profile used in semiconductor equipment frames, panels, and structural assemblies (with a thickness of 6.3 mm or less); fabricated aluminum articles including brackets, supports, clamps, shields, or mounting hardware used in semiconductor manufacturing equipment; titanium metal plate, bar, fitting, or fabricated article used for corrosion-resistant semiconductor chemical and vacuum process applications; fixed spanners and wrenches used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; vises and clamps used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; metal fittings and brackets used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; metal mountings and fittings used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; flexible stainless steel or metal hose assembly with braided reinforcement for high-purity gas and vacuum transfer systems (w/fittings); flexible stainless steel or metal hose assembly with braided reinforcement for high-purity gas and vacuum transfer systems; metal plates used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; industrial centrifugal, diaphragm, or fluid transfer pump component used in semiconductor

chemical delivery and recirculation systems; vacuum pump, gas compressor, blower, or related assembly used for semiconductor wafer processing and vacuum chamber operations; tight biological safety cabinets; industrial heat exchange, thermal processing, cooling, or temperature control apparatus used in semiconductor manufacturing equipment; industrial gas, liquid, or vacuum filtration and purification apparatus including filter housing and replaceable filter elements for semiconductor process systems; air filters for industrial gas, liquid, or vacuum filtration and purification apparatus including filter housings and replaceable filter elements for semiconductor process systems; dust collectors for industrial gas, liquid, or vacuum filtration and purification apparatus including filter housings and replaceable filter elements for semiconductor process systems; gas separation equipment for industrial gas, liquid, or vacuum filtration and purification apparatus including filter housing and replaceable filter elements for semiconductor process systems; gas filters for industrial gas, liquid, or vacuum filtration and purification apparatus including filter housings and replaceable filter elements for semiconductor process systems; filter housing for semiconductor process systems; cleaning machines used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; clean strap, lock plate used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; sand blasting machine used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; lathe collets; hand grinders (polishers and sanders) used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; automatic data processing unit, controller, or industrial computer hardware used for semiconductor equipment monitoring and automation; pcbas used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; populated printed circuit board for test or development activities development; air humidifiers/dehumidifiers used in semiconductor manufacturing systems; specialized electro-mechanical motors used in semiconductor manufacturing systems; clip, cam shaft for electro-mechanical motors used in semiconductor manufacturing systems; pressure-

reducing valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems; pressure-reducing valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems (hydraulic); pressure-reducing valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems (having a pressure rating under 850kpa); pressure-reducing valve with machined metal (steel) body used to regulate process gas flow in semiconductor fluid delivery systems; pressure-reducing valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems (having a pressure rating of 850 kpa or over); pressure-reducing, ball-type valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems; hand-operated, pressure-reducing valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems; pressure-reducing, solenoid valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems; regulator valve with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems; pressure-reducing valve with machined metal body designed for proportional operation by a signal from a control device used to regulate process gas flow in semiconductor fluid delivery systems; pressure-reducing and thermostatically controlled valve with machined metal body and pneumatic actuators used to regulate process gas flow in semiconductor fluid delivery systems; thermostatically controlled gate valve with machined metal body and pneumatic actuators used to regulate process gas flow in semiconductor fluid delivery systems—gate valve, regulator, actuator, flow restrictor, orifice; pressure-reducing valve bodies with machined metal body used to regulate process gas flow in semiconductor fluid delivery systems; parts of pressure-reducing and thermostatically controlled valve with machined metal body (steel forging) and pneumatic actuators used to regulate process gas flow in semiconductor fluid delivery systems; gas panel sub-assembly kits used in semiconductor device manufacturing; parts of gas panel for semiconductor device manufacturing, such as mounting brackets, purge assembly, side panels or enclosures; electric motors used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation

applications (motors of an output not exceeding 37.5 w > of 18.65 w or more but not exceeding 37.5 w > other of 18.65w or more but not exceeding 37.5 w); electric motors used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications (universal ac/dc motors of an output exceeding 37.5 w > exceeding 74.6 w but not exceeding 735 w); single-phase electric motors used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; static converter, power supply, transformer, reactor, or electrical power conditioning assembly for electric motors used in semiconductor manufacturing equipment; power supply for static converter, power supply, transformer, reactor, or electrical power conditioning assembly for electric motors used in semiconductor manufacturing equipment (with a power output exceeding 150 w but not exceeding 500 w); power supply for static converter, power supply, transformer, reactor, or electrical power conditioning assembly for electric motors used in semiconductor manufacturing equipment; static converter, power supply, transformer, reactor, or electrical power conditioning assembly used in semiconductor manufacturing equipment; parts of static converter, power supply, transformer, reactor, or electrical power conditioning assembly used in semiconductor manufacturing equipment; metal electromagnets used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of metal electromagnets used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of welding apparatus used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; heating resistors used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; switching apparatus used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of switching apparatus in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; lcd screens used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of electrical capacitors used in semiconductor manufacturing, fluid handling, vacuum

processing, or industrial automation applications; carbon film, electrical resistors used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of heating resistors used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; printed circuit boards used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; rotary switches not over 5 a rating used in semiconductor manufacturing equipment and industrial automation systems; rotary switches over 5 a rating used in semiconductor manufacturing equipment and industrial automation systems; optical fiber cables used in semiconductor manufacturing equipment and industrial automation systems; lamp holders, plugs and sockets used in semiconductor manufacturing equipment and industrial automation systems; electrical couplings used in semiconductor manufacturing equipment and industrial automation systems; electrical junction boxes used in semiconductor manufacturing equipment and industrial automation systems; electric power distribution panel boards used for semiconductor manufacturing and process automation equipment (for a voltage not exceeding 1,000 v > other for a voltage not exceeding 1,000 v); electric panel boards used for semiconductor manufacturing and processing automation equipment (for a voltage not exceeding 1,000 v > other for a voltage not exceeding 1,000 v); parts of electrical enclosure, panel hardware, contact assembly, or control cabinet component used in semiconductor equipment electrical systems; printed circuit assemblies for electrical enclosure, panel hardware, contact assembly, or control cabinet component used in semiconductor equipment electrical systems; molded parts for electrical enclosure, panel hardware, contact assembly, or control cabinet component used in semiconductor equipment electrical systems; parts of led lamps designed for a voltage not exceeding 100 v used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; diodes for led lamps used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; electrical signal generators used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; pipe sealing machines, purge panels, and

other accessories used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; insulated electrical conductor, cable, fiber optic assembly, or wiring harness with connectors for telecommunications (ethernet) used in semiconductor manufacturing equipment (for a voltage not exceeding 1,000 v); insulated electrical conductor, cable, fiber optic assembly, or wiring harness with connectors used in semiconductor manufacturing equipment (for a voltage not exceeding 1,000 v); cable assembly for control valve used in semiconductor manufacturing equipment; coated fiber glass insulator; convex lens used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of microscope used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; handheld sealer assembly; thermocouple and other floating instruments used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of thermocouples and other floating instruments used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; humidity sensor communication module used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; humidity sensors; parts of electronic instrument for measuring or monitoring liquid, gas, pressure, or flow characteristics in semiconductor process systems; pressure gauges and manometers; electronic instrument for measuring or monitoring liquid, gas, pressure, or flow characteristics in semiconductor process systems (gauge caps, manometers, pressure transducer); spectrum analyzer with recorder used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of spectrum analyzer used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; gas boxes used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; parts of gas boxes used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications; quartz rod for measurement used in semiconductor manufacturing, fluid handling, vacuum processing, or industrial automation applications;

pneumatic manifold or control instrument incorporating electronic sensing and feedback functions for semiconductor manufacturing equipment; parts of pneumatic manifold, automatic regulating or control instrument incorporating electronic sensing and feedback functions for semiconductor manufacturing equipment; pressure controller for gas or liquids for semiconductor manufacturing equipment; mass flow controller of gas or liquids for semiconductor manufacturing equipment; pressure controller panel mount for semiconductor manufacturing equipment; parts of pressure transducer or flow controller for semiconductor manufacturing equipment; metals parts of pressure transducer or flow controller for semiconductor manufacturing equipment; and al or stainless steel brackets for gas panels for semiconductor equipment (duty rate ranges from duty-free to 8.6%).

The request indicates that certain materials/components are subject to duties under section 232 of the Trade Expansion Act of 1962 (section 232) depending on the country of origin. The applicable section 232 decision requires subject merchandise to be admitted to FTZs in privileged foreign status (19 CFR 146.41). The request also indicates that parts of gas panel for semiconductor device manufacturing, such as mounting brackets, purge assembly, side panels or enclosures; and fabricated aluminum articles including brackets, supports, clamps, shields, or mounting hardware used in semiconductor manufacturing equipment are subject to an antidumping/countervailing duty (AD/CVD) order/investigation if imported from certain countries. The Board's regulations (15 CFR 400.13(c)(2)) require that merchandise subject to AD/CVD orders, or items which would be otherwise subject to suspension of liquidation under AD/CVD procedures if they entered U.S. customs territory, be admitted to the zone in privileged foreign status (19 CFR 146.41).

Public comment is invited from interested parties. Submissions shall be addressed to the Board's Executive Secretary and sent to: ftz@trade.gov. The closing period for their receipt is October 5, 2026.

A copy of the notification will be available for public inspection in the "Online FTZ Information System" section of the Board's website.

For further information, contact John Frye at John.Frye@trade.gov.

Dated: August 20, 2026.
Elizabeth Whiteman,
Executive Secretary.
 [FR Doc. 2026–17241 Filed 8–21–26; 8:45 am]
BILLING CODE 3510–DS–P

DEPARTMENT OF COMMERCE

Foreign-Trade Zones Board

[B–103–2026]

Foreign-Trade Zone (FTZ) 23, Notification of Proposed Production Activity; Niagara Specialty Metals; (Steel Sheets); Akron, New York

Niagara Specialty Metals submitted a notification of proposed production activity to the FTZ Board (the Board) for its facility in Akron, New York within FTZ 23. The notification conforming to the requirements of the Board's regulations (15 CFR 400.22) was received on August 19, 2026.

Pursuant to 15 CFR 400.14(b), FTZ production activity would be limited to the specific foreign-status material(s)/component(s) and specific finished product(s) described in the submitted notification (summarized below) and subsequently authorized by the Board. The benefits that may stem from conducting production activity under FTZ procedures are explained in the background section of the Board's website—accessible via www.trade.gov/ftz.

The proposed finished products include high speed steel sheets, stainless steel sheets, tool steel sheets, alloy steel cut into shapes per customer specifications, and alloy steel sheets (duty-free).

The proposed foreign-status materials/components include stainless steel slabs, alloy steel slabs, and high speed steel slabs (duty-free).

The request indicates that certain materials/components are subject to duties under section 232 of the Trade Expansion Act of 1962 (section 232) depending on the country of origin. The applicable section 232 decisions require subject merchandise to be admitted to FTZs in privileged foreign status (19 CFR 146.41).

Public comment is invited from interested parties. Submissions shall be addressed to the Board's Executive Secretary and sent to: ftz@trade.gov. The closing period for their receipt is October 5, 2026.

A copy of the notification will be available for public inspection in the "Online FTZ Information System" section of the Board's website.

For further information, contact Brian Warnes at brian.warnes@trade.gov.

Dated: August 19, 2026.
Elizabeth Whiteman,
Executive Secretary.
 [FR Doc. 2026–17195 Filed 8–21–26; 8:45 am]
BILLING CODE 3510–DS–P

DEPARTMENT OF COMMERCE

International Trade Administration

Initiation of Antidumping and Countervailing Duty Administrative Reviews

Correction

In notice document 2026–04516, appearing on pages 11274–11287, in the issue of Monday, March 9, 2026, make the following correction:

On page 11286, in the table, the last row of the table was inadvertently omitted and should read, "Longi Technology SDN".

[FR Doc. C1–2026–04516 Filed 8–21–26; 8:45 am]
BILLING CODE 0099–10–D

DEPARTMENT OF COMMERCE

National Oceanic and Atmospheric Administration

[RTID 0648–XF972]

Western Pacific Fishery Management Council; Public Meetings

AGENCY: National Marine Fisheries Service (NMFS), National Oceanic and Atmospheric Administration (NOAA), Commerce.

ACTION: Notice of public meetings.

SUMMARY: The Western Pacific Fishery Management Council (Council) will hold its 161st Scientific and Statistical Committee (SSC), Executive and Budget Standing Committee (SC), and 208th Council meetings to take actions on fishery management issues in the Western Pacific Region.

DATES: The meetings will be held between September 8 and September 17, 2026. For specific times and agendas, see **SUPPLEMENTARY INFORMATION**. Written public comments on final action items at the 208th Council meeting should be received at the Council office by 5 p.m. HST, Thursday, September 10, 2026, see **ADDRESSES**.

ADDRESSES: 161st SSC will be held as hybrid meetings for members and the public, with a remote participation option available via Webex. In-person attendance for the 161st SSC meeting will be hosted at the Council office, 1164 Bishop Street, Suite 1400, Honolulu, HI 96813.